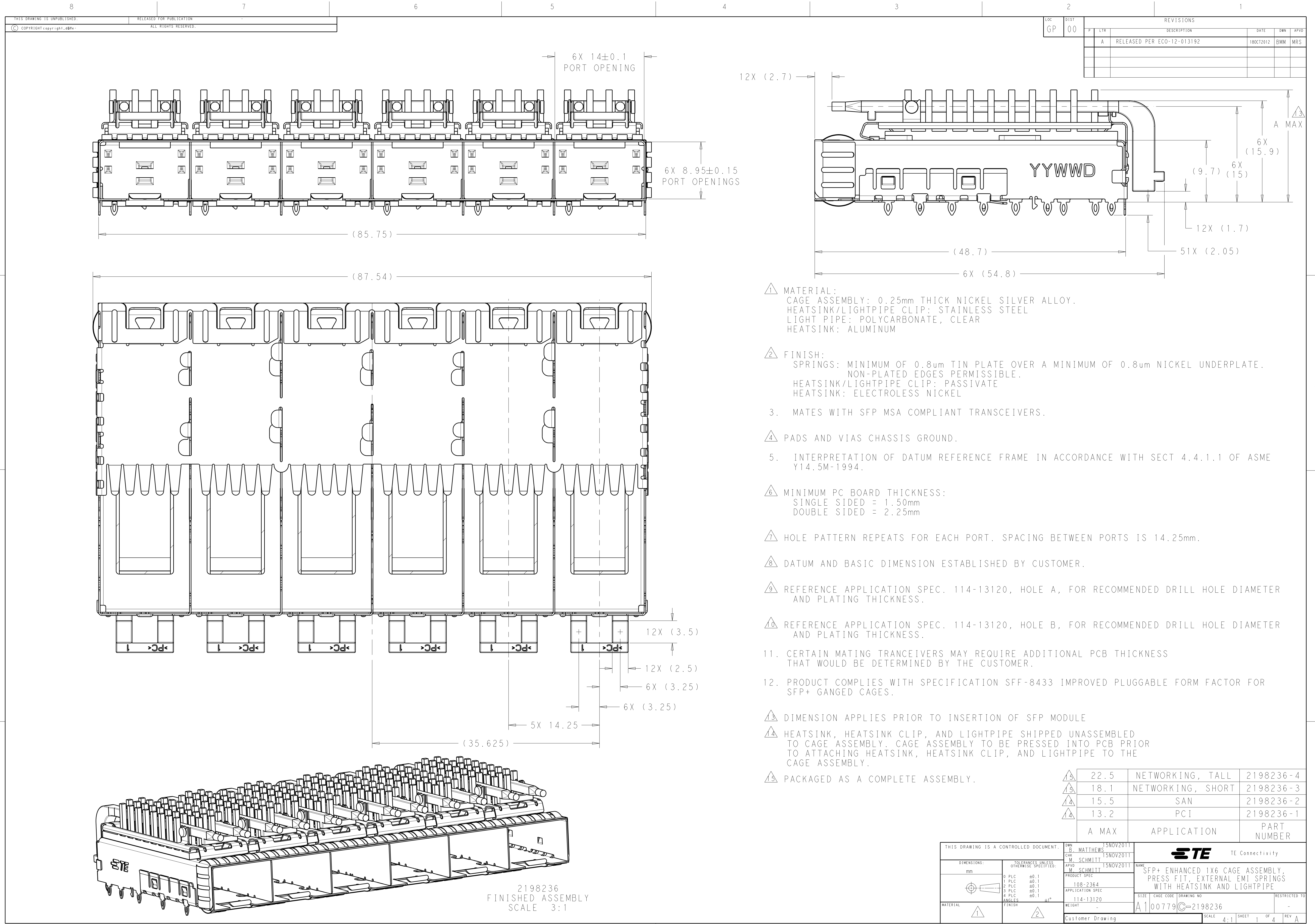




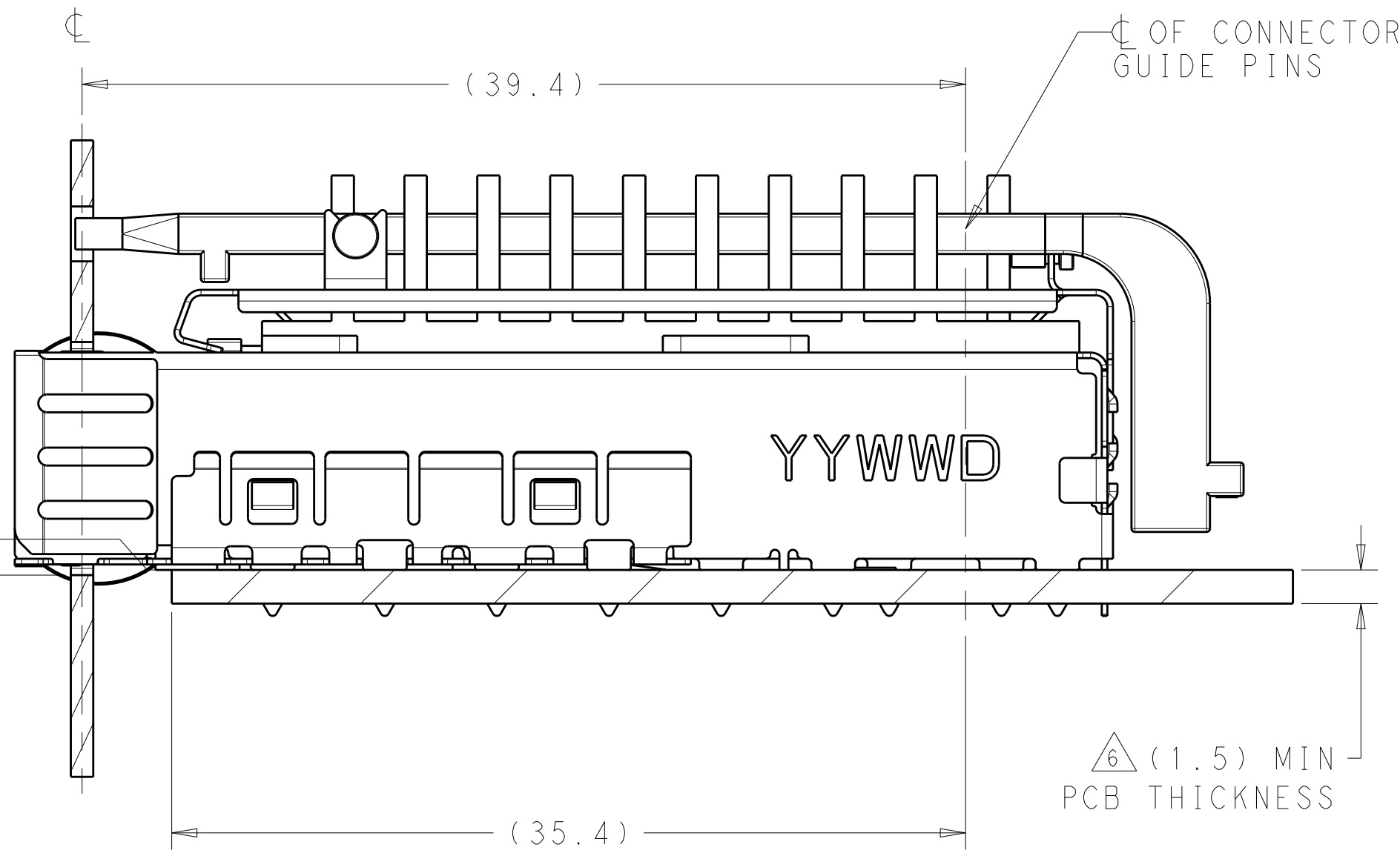
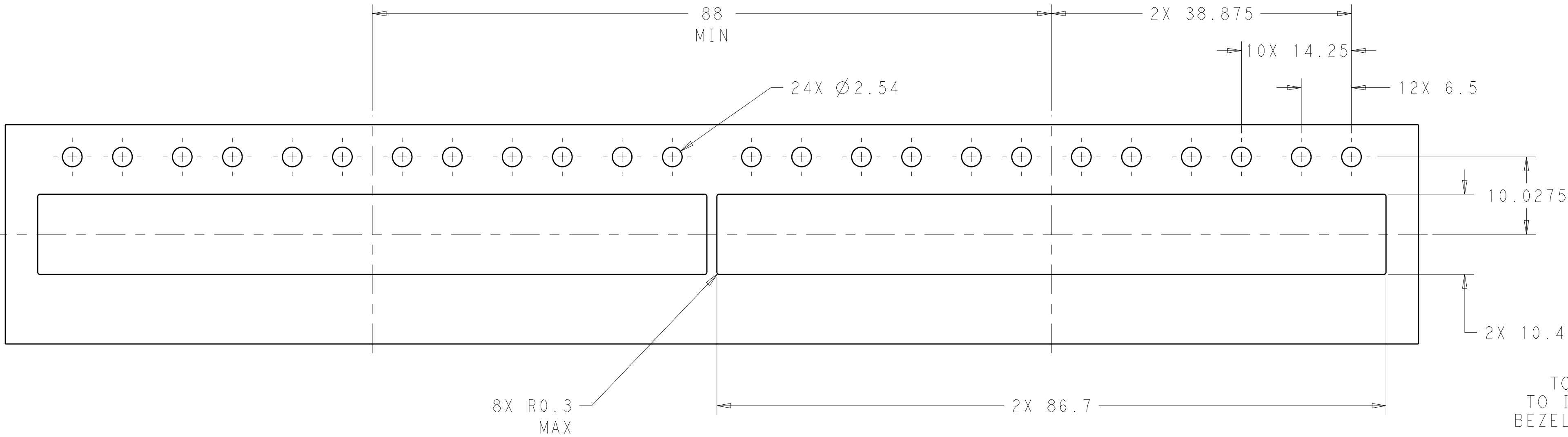
LOC		DIST		REVISIONS					
GP		00		P	LTR	DESCRIPTION	DATE	DWN	APVD
					A	RELEASED PER ECO-12-013192	180C12012	BMM	MRS

- 1 MATERIAL:
CAGE ASSEMBLY: 0.25mm THICK NICKEL SILVER ALLOY.
HEATSINK/LIGHTPIPE CLIP: STAINLESS STEEL
LIGHT PIPE: POLYCARBONATE, CLEAR
HEATSINK: ALUMINUM
- 2 FINISH:
SPRINGS: MINIMUM OF 0.8um TIN PLATE OVER A MINIMUM OF 0.8um NICKEL UNDERPLATE.
NON-PLATED EDGES PERMISSIBLE.
HEATSINK/LIGHTPIPE CLIP: PASSIVATE
HEATSINK: ELECTROLESS NICKEL
3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 4 PADS AND VIAS CHASSIS GROUND.
5. INTERPRETATION OF DATUM REFERENCE FRAME IN ACCORDANCE WITH SECT 4.4.1.1 OF ASME Y14.5M-1994.
- 6 MINIMUM PC BOARD THICKNESS:
SINGLE SIDED = 1.50mm
DOUBLE SIDED = 2.25mm
- 7 HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 14.25mm.
- 8 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 9 REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 10 REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
11. CERTAIN MATING TRANSCEIVERS MAY REQUIRE ADDITIONAL PCB THICKNESS THAT WOULD BE DETERMINED BY THE CUSTOMER.
12. PRODUCT COMPLIES WITH SPECIFICATION SFF-8433 IMPROVED PLUGGABLE FORM FACTOR FOR SFP+ GANGED CAGES.
- 13 DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE
- 14 HEATSINK, HEATSINK CLIP, AND LIGHTPIPE SHIPPED UNASSEMBLED TO CAGE ASSEMBLY. CAGE ASSEMBLY TO BE PRESSED INTO PCB PRIOR TO ATTACHING HEATSINK, HEATSINK CLIP, AND LIGHTPIPE TO THE CAGE ASSEMBLY.
- 15 PACKAGED AS A COMPLETE ASSEMBLY.

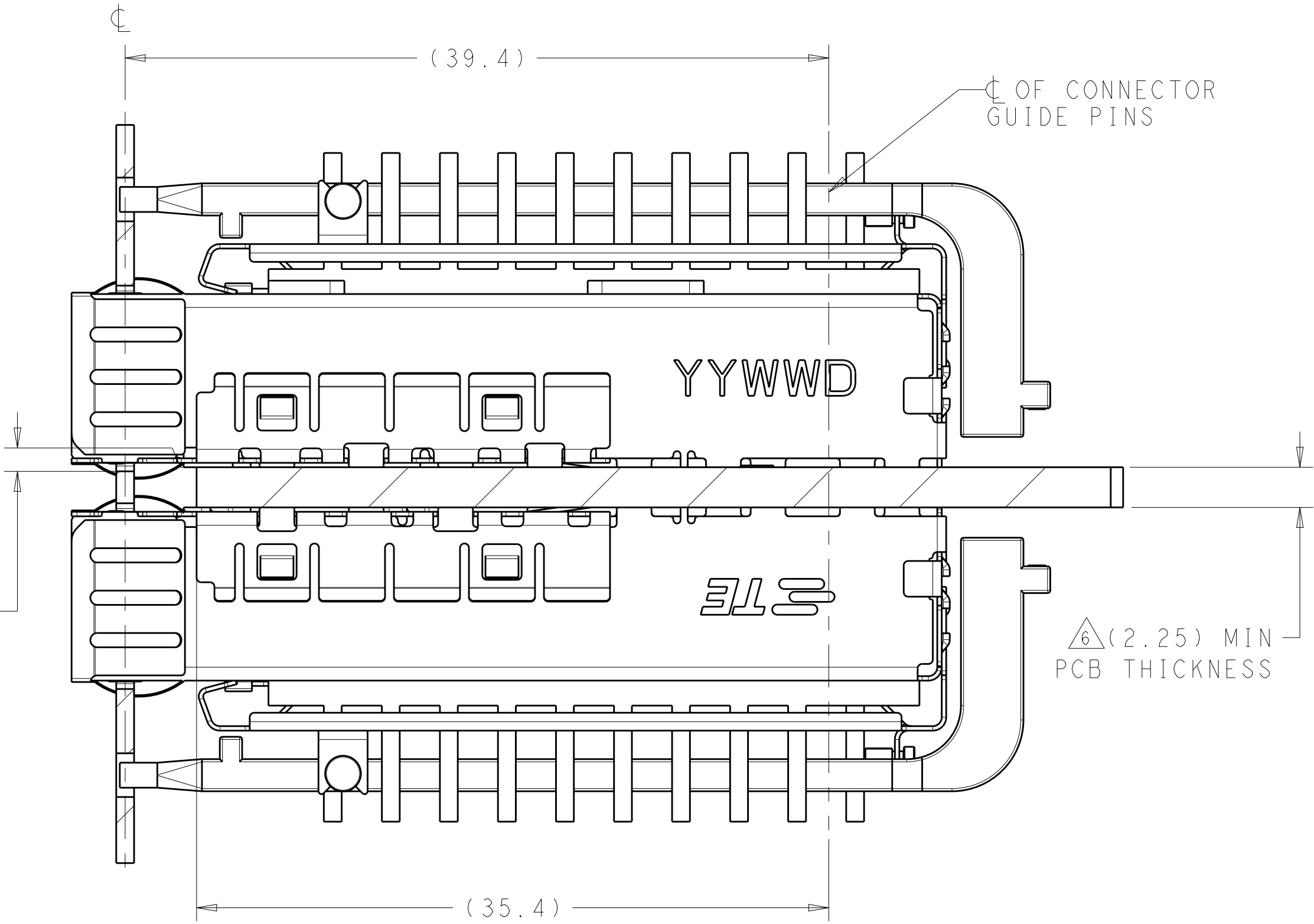
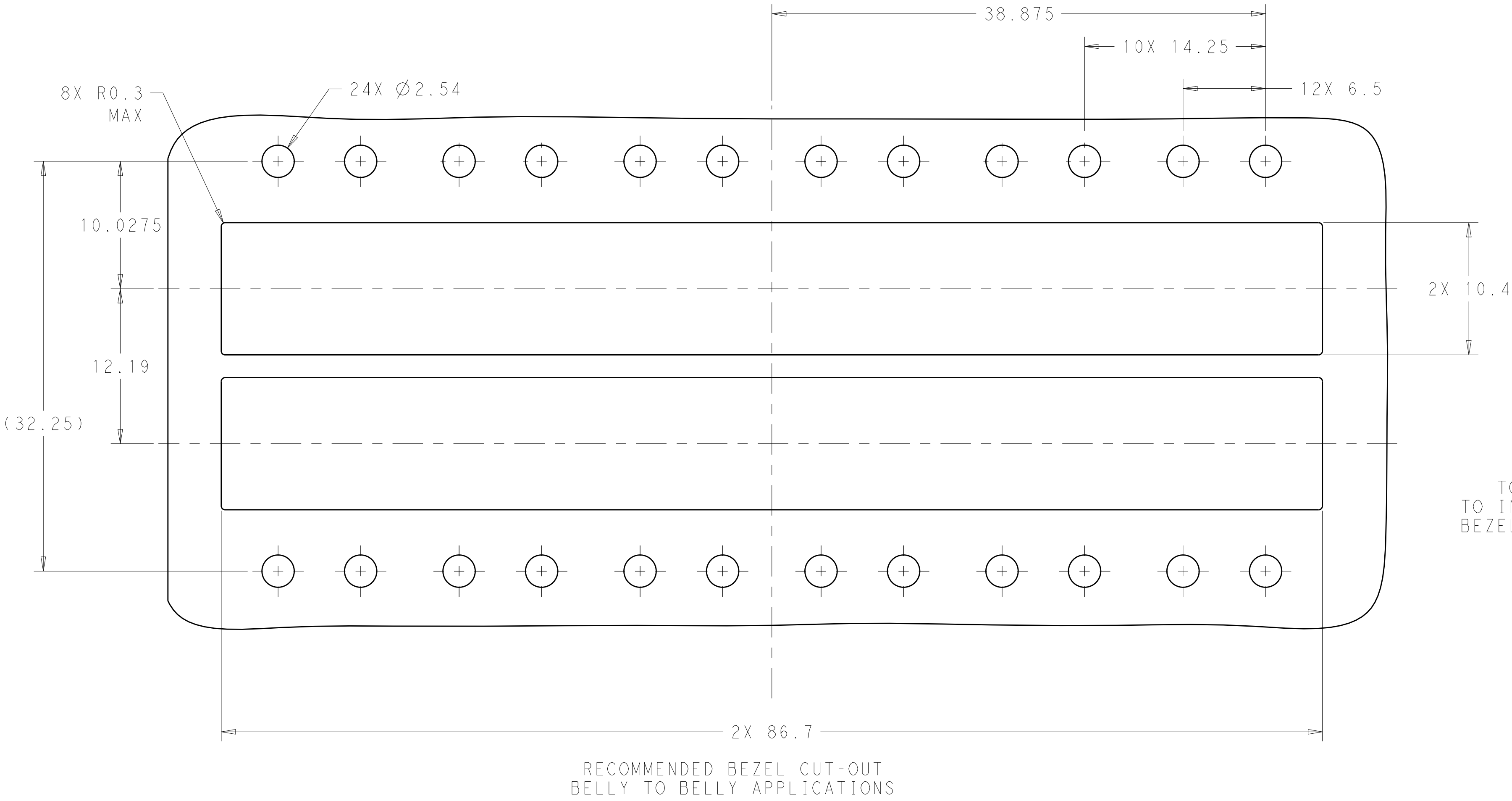
22.5	NETWORKING, TALL	2198236-4
18.1	NETWORKING, SHORT	2198236-3
15.5	SAN	2198236-2
13.2	PCI	2198236-1
A MAX	APPLICATION	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. MATTHEWS 15NOV2011	 TE Connectivity	
DIMENSIONS: mm		CHK M. SCHMITT 15NOV2011		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD M. SCHMITT 15NOV2011	NAME SFP+ ENHANCED 1X6 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE	
0 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1 ANGLES ±0.1		PRODUCT SPEC 108-2364 APPLICATION SPEC 114-13120	SIZE A100779	
MATERIAL		WEIGHT	CAGE CODE C=2198236	
FINISH		Customer Drawing	RESTRICTED TO SCALE 4:1 SHEET 1 OF 4 REV A	

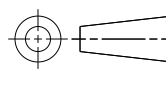
LOC		DIST		REVISONS			
GP		P	LTR	DESCRIPTION	DATE	DWN	APVD
		-		SEE SHEET 1	-	-	-

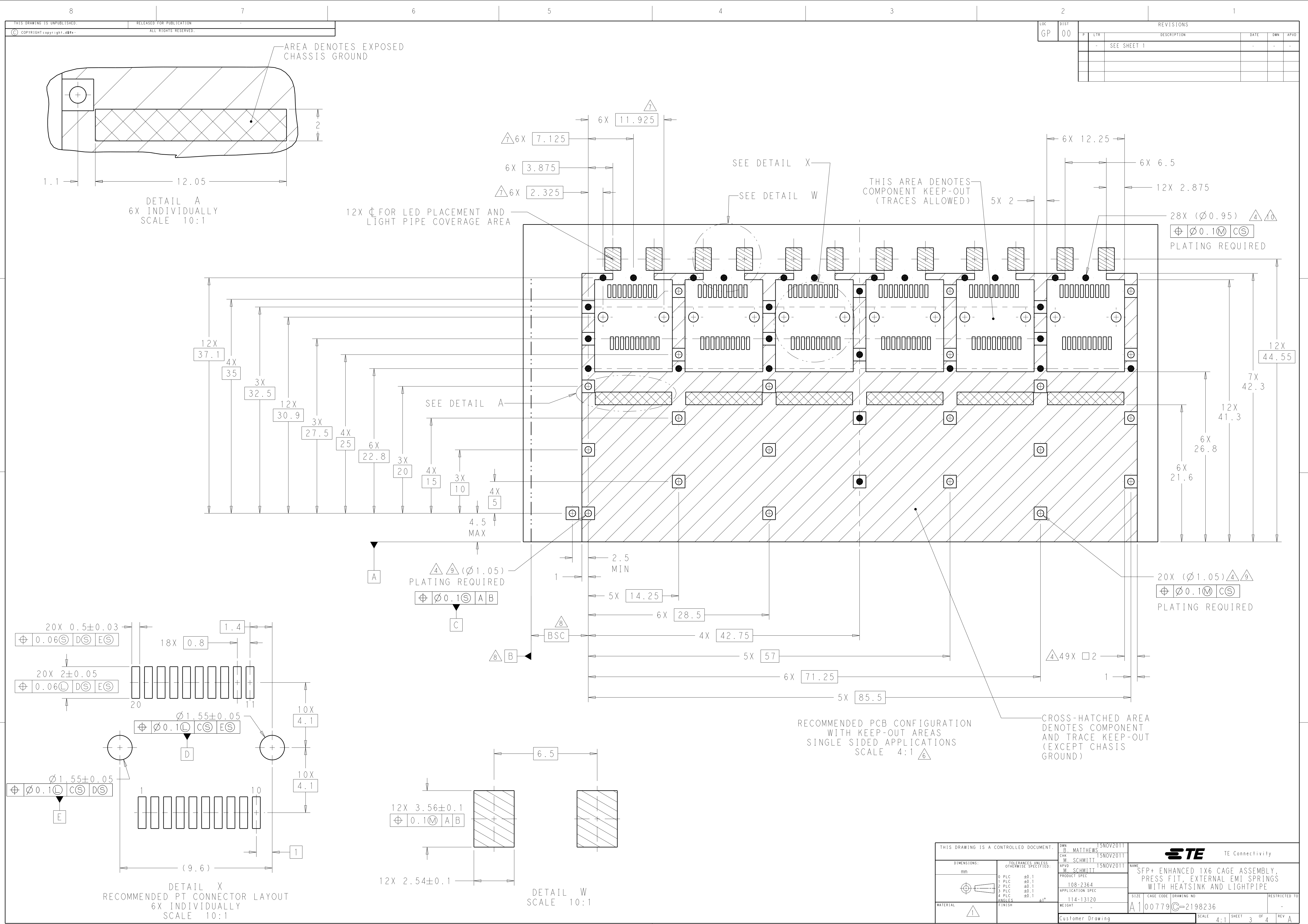


2198236
MOUNTED ON PC BOARD
SHOWN THRU RECOMMENDED BEZEL



2198236
MOUNTED BELLY TO BELLY ON PC BOARD
SHOWN THRU RECOMMENDED BEZEL

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. MATTHEWS 15NOV2011	 TE Connectivity	
DIMENSIONS:		CHK M. SCHMITT 15NOV2011		
mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD M. SCHMITT 15NOV2011	NAME SFP+ ENHANCED 1X6 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE	
	0 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1 ANGLES ±1° FINISH	PRODUCT SPEC 108-2364 APPLICATION SPEC 114-13120	SIZE A1	
MATERIAL		WEIGHT -	CAGE CODE 100779	
Customer Drawing		DRAWING NO 2198236		RESTRICTED TO -
		SCALE 4:1		SHEET 2 OF 4
				REV A



LOC		DIST		REVISONS			
GP		00		DATE	OWN	APVD	
				DESCRIPTION	DATE	OWN	APVD
				SEE SHEET 1	-	-	-



12X C FOR LED PLACEMENT AND
LIGHT PIPE COVERAGE AREA



RECOMMENDED PCB CONFIGURATION
WITH KEEP-OUT AREAS
BELLY TO BELLY APPLICATIONS
SCALE 4:1 

—CROSS-HATCHED AREA
DENOTES COMPONENT
AND TRACE KEEP-OUT
(EXCEPT CHASSIS
GROUND)



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN D. MATTHEWS	15NOV2011		
		CWK M. SCHMITT	15NOV2011	 TE Connectivity	
DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME	
mm		APVD M. SCHMITT	15NOV2011	SFP+ ENHANCED 1X6 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE	
	0 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1 ANGLES ±1°	PRODUCT SPEC 108-2364 APPLICATION SPEC 114-13120		SIZE CAGE CODE DRAWING NO. A1 00779 ©=2198236	
MATERIAL	FINISH	WEIGHT	-	RESTRICTED TO	
		Customer Drawing		SCALE A : 1	SHEET 4 OF 4 REV A

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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